

1. Scope :

This specification applies to silicon one-dimensional PSD chips, Device No. PSD-00092-B.

2. Structure :

- 2-1. Planar type : PIN.
- 2-2. Electrodes :
 Top side(Anode 1 & Anode 2) : Aluminum alloy.
 Back side (Cathode) : Gold.

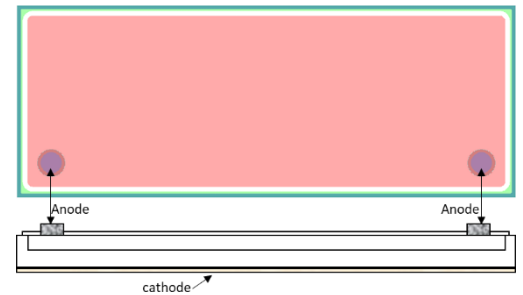
3. Size :

- 3-1. Chip size (including scribe lane) : 149.6 mils x 57.4 mils (3.8 mm x 1.46 mm).
- 3-2. Chip thickness : 12 ± 1.0 mils (0.305 ± 0.025 mm).
- 3-3. Active area : 143.3 mils x 51.1 mils (3.64 mm x 1.3 mm).
- 3-4. Bonding pad (Anode) : 7.87 ± 0.394 mils (0.20 ± 0.010 mm) Diameter
- 3-5. Pattern drawing : Refer to the attached drawing..

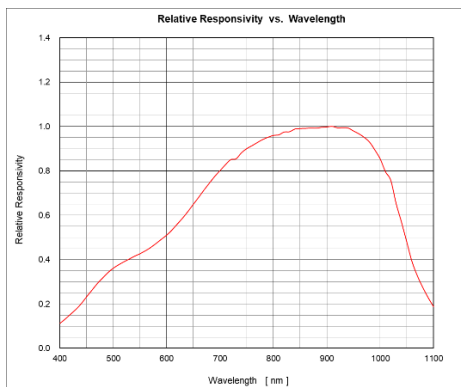
4. Electrical characteristics (Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
* Reverse dark current	I_D	$V_R=10V$ $E_e=0mW/cm^2$			10	nA
* Reverse breakdown voltage	$V_{(BR)R}$	$I_R=100\mu A$ $E_e=0mW/cm^2$	60			V
Reverse light current	I_L	$V_R = 1V$ $\lambda_p=940nm$ $E_e=1mW/cm^2$		26		μA
Junction Capacitance	C_J	$V_R= 1V$ $f= 10KHz$		20		pF
* Interelectrode Resistance	R_T	$V_R=0.1V$	40		60	$K\Omega$
Radiant Sensitivity	S_λ	$\lambda_p=940nm$		0.55		A/W
Spectral Response	SR		400 - 1100			nm

*Based on 100% probing



5. Relative spectral responsivity



*bare chip measured with integrating sphere, for reference only.